

# TECHNICAL REPORT

# RAPPORT TECHNIQUE

**Environmental testing –  
Part 3-12: Supporting documentation and guidance – Method to evaluate a  
possible lead-free solder reflow temperature profile**

**Essais d'environnement –  
Partie 3-12: Documentation d'accompagnement et guide – Méthode d'évaluation  
d'un profil de température possible de brasage sans plomb par refusion**



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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

## ENVIRONMENTAL TESTING –

**Part 3-12: Supporting documentation and guidance –  
Method to evaluate a possible lead-free solder  
reflow temperature profile**

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IEC TR 60068-3-12, which is a technical report, has been prepared by IEC technical committee 91: Electronics assembly technology.

This second edition cancels and replaces the first edition published in 2007 and constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- the content has been adapted to the state-of-the-art of reflow-oven technology and termination finishes;
- minor language adjustments were performed.

The text of this technical report is based on the following documents:

Enquiry draft	Report on voting
91/1158/DTR	91/1177/RVC

Full information on the voting for the approval of this technical report can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all the parts in the IEC 60068 series, under the general title *Environmental testing*, can be found on the IEC website.

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